

PRODUCT RELIABILITY REPORT FOR

DS1392, Rev A2 (1.8V, 3.0V & 3.3V)

Dallas Semiconductor

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Prepared by:

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Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products:

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at http://www.maxim-ic.com/TechSupport/dsreliability.html.

Device Description:

A description of this device can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.

Reliability Derating:

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

```
AfT = exp((Ea/k)*(1/Tu - 1/Ts)) = tu/ts
AfT = Acceleration factor due to Temperature
tu = Time at use temperature (e.g. 55°C)
ts = Time at stress temperature (e.g. 125°C)
k = Boltzmann's Constant (8.617 x 10-5 eV/°K)
Tu = Temperature at Use (°K)
Ts = Temperature at Stress (°K)
Ea = Activation Energy (e.g. 0.7 ev)
```

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

```
AfV = exp(B*(Vs - Vu))
AfV = Acceleration factor due to Voltage
Vs = Stress Voltage (e.g. 7.0 volts)
Vu = Maximum Operating Voltage (e.g. 5.5 volts)
B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)
```

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

```
Fr = X/(ts * AfV * AfT * N * 2)
X = Chi-Sq statistical upper limit
N = Life test sample size
```

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

MTTF = 1/Fr

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

FAILURE RATE: MTTF (YRS): 98971 FITS: 1.2

The parameters used to calculate this failure rate are as follows:

Cf: 60% Ea: 0.7 B: 0 Tu: 25 °C Vu: 3.3 Volts

The reliability data follows. A the start of this data is the device information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available and may contain some generic data. "*" after DATE CODE denotes specific product data.

Device Information:

Process: D6H-2P2M,HPVt,TCN1 ALOCOS:GOI Passivation: Passivation w/Nov TEOS Oxide-Nitride

Die Size: 62 x 87

Number of Transistors: 1

Interconnect: Aluminum / 1% Silicon / 0.5% Copper

Gate Oxide Thickness: 150 Å

ELECTRICAL CHARACTERIZATION

HIGH VOLTAGE LIFE 0310

DESCRIPTION	DATE CODE CONDITION		READPOINT		QTY	FAILS	FA#
ESD SENSITIVITY	0421 *	EOS/ESD S5.1 HBM 500 VOLTS	1	PUL'S	3	0	
ESD SENSITIVITY	0421 *	EOS/ESD S5.1 HBM 1000 VOLTS	1	PUL'S	3	0	
ESD SENSITIVITY	0421 *	EOS/ESD S5.1 HBM 2000 VOLTS	1	PUL'S	3	0	
ESD SENSITIVITY	0421 *	EOS/ESD S5.1 HBM 4000 VOLTS	1	PUL'S	3	0	
ESD SENSITIVITY	0421 *	EOS/ESD S5.1 HBM 8000 VOLTS	1	PUL'S	3	3	No FA
LATCH-UP	0421 *	JESD78, I-TEST 25C	2	DYS	6	0	
LATCH-UP	0421 *	JESD78, Vsupply TEST 125C	2	DYS	6	0	
LATCH-UP	0421 *	JESD78, I-TEST 85C	2	DYS	6	0	
LATCH-UP	0421 *	JESD78, I-TEST 85C	2	DYS	6	0	
				Total:		3	

OPERATING LIFE						
DESCRIPTION	DATE CODE CONDITION		READPOINT	QTY	FAILS	FA#
HIGH VOLTAGE LIFE	0302	125C, 6.0 VOLTS	1000 HRS	77	0	
HIGH VOLTAGE LIFE	0306	125C, 4.9 V (PSA) & 3.6 V (PSB)	1000 HRS	45	0	
HIGH VOLTAGE LIFE	0307	125C, 6.0 VOLTS	1000 HRS	77	0	
HIGH VOLTAGE LIFE	0310	125C, 6.0 VOLTS	1000 HRS	80	0	
HIGH VOLTAGE LIFE	0310	125C, 6.0 VOLTS	1000 HRS	45	0	

1000 HRS

45

0

125C, 6.0 VOLTS

			•	Total:		0
HIGH TEMP OP LIFE	0424	125C, 5.5 VOLTS	192	HRS	45	0
HIGH TEMP OP LIFE	0422	125C, 5.5 VOLTS	192	HRS	45	0
HIGH TEMP OP LIFE	0421	125C, 5.5 VOLTS	1000	HRS	45	0
HIGH TEMP OP LIFE	0421 *	125C, 5.5 VOLTS	1000	HRS	45	0
HIGH TEMP OP LIFE	0403	125C, 5.5 VOLTS	1000	HRS	77	0
HIGH TEMP OP LIFE	0403	125C, 3.6 VOLTS	1000	HRS	45	0
HIGH TEMP OP LIFE	0324	125C, 5.25 VOLTS	1000	HRS	45	0
HIGH TEMP OP LIFE	0318	125C, 5.5 VOLTS	1000	HRS	77	0
HIGH TEMP OP LIFE	0312	125C, 3.3 VOLTS	1000	HRS	45	0
HIGH TEMP OP LIFE	0311	125C, 3.5 VOLTS	1000	HRS	77	0

FAILURE RATE: MTTF (YRS): 98971 FITS: 1.2

The DS1392 1.8V and 3.0V devices pass Latchup I-Test at 85C. The DS1392 3.3V device passes Latchup I-Test at 25C and is marginal at 85C.